

Refine Search

Search Results -

Terms	Documents
(subsrate) and (remove insulation)	0

US Pre-Grant Publication Full-Text Database US Patents Full-Text Database US OCR Full-Text Database

Database:

EPO Abstracts Database
JPO Abstracts Database
Derwent World Patents Index
IBM Technical Disclosure Bulletins

Search:

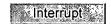
L46



Refine Search







Search History

DATE: Monday, October 04, 2004 Printable Copy Create Case

Set Name side by side	Query	Hit Count	Set Name result set		
-	B, USPT, USOC, EPAB, JPAB, DWPI, TDBD; PLUR=YE	ES; OP=ADJ			
<u>L46</u>	(subsrate) and (remove insulation)	0	<u>L46</u>		
<u>L45</u>	L44 and "insulation"	11	<u>L45</u>		
<u>L44</u>	(contact thermocouple) and (substrate)	126	<u>L44</u>		
DB=PGP	B; PLUR=YES; OP=ADJ				
<u>L43</u>	L1 and "substrate"	1	<u>L43</u>		
DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ					
<u>L42</u>	L41 and "semiconductor wafer"	23	<u>L42</u>		
<u>L41</u>	thin film thermocouple	227	<u>L41</u>		
DB=PGPB; PLUR=YES; OP=ADJ					
<u>L40</u>	L1 and "extends"	1	<u>L40</u>		
<u>L39</u>	L1 and "extends beyond an edge"	0	<u>L39</u>		
DB = PGPB, $USPT$, $USOC$, $EPAB$, $JPAB$, $DWPI$, $TDBD$; $PLUR = YES$; $OP = ADJ$					
<u>L38</u>	junction on substrate	0	<u>L38</u>		
<u>L37</u>	L20 and "thin film thermocouple"	42	<u>L37</u>		

<u>L36</u>	L35 and "thermocouple"	83	<u>L36</u>
<u>L35</u>	measure substrate temperature	149	<u>L35</u>
<u>L34</u>	junction on bare substrate	0	<u>L34</u>
<u>L33</u>	temperature instrumented .	12	<u>L33</u>
DB = USP	T; PLUR=YES; OP=ADJ		
<u>L32</u>	6472240.pn.	1	<u>L32</u>
DB=PGP	PB, USPT, USOC, EPAB, JPAB, DWPI; PLUR=YES; OP=ADJ	ī	
<u>L31</u>	temperature instrumented semiconductor	3	<u>L31</u>
DB=PGF	PB; PLUR=YES; OP=ADJ		
<u>L30</u>	temperature instrumented semiconductor	1	<u>L30</u>
DB = USP	T; PLUR=YES; OP=ADJ		
<u>L29</u>	L20 and "Laof"	0	<u>L29</u>
DB=PGF	PB; PLUR=YES; OP=ADJ		
<u>L28</u>	L27 and "thermocouple"	3	<u>L28</u>
<u>L27</u>	schuh	132	<u>L27</u>
DB=PGF	PB, USPT, USOC, EPAB, JPAB, DWPI, TDBD; PLUR=YES; O.	P=ADJ	
<u>L26</u>	temperature indicating wafer	2	<u>L26</u>
<u>L25</u>	temperature calibrating wafer	1	<u>L25</u>
<u>L24</u>	L21 and "SenseArray"	0	<u>L24</u>
<u>L23</u>	L21 and "thermocouple"	224	<u>L23</u>
<u>L22</u>	L21 and "hot junction"	1	<u>L22</u>
<u>L21</u>	L20 and "temperature wafer"	350	<u>L21</u>
<u>L20</u>	374/\$	33203	<u>L20</u>
<u>L19</u>	temperature wafer	6691	<u>L19</u>
<u>L18</u>	hot junction formed on substrate	0	<u>L18</u>
<u>L17</u>	L16 and "insulation"	34	<u>L17</u>
<u>L16</u>	forming hot junction	85	<u>L16</u>
<u>L15</u>	L12 and "hot junction"	18	<u>L15</u>
<u>L14</u>	L12 and "hot junction"	18	<u>L14</u>
<u>L13</u>	L12 and "substrate"	13	<u>L13</u>
<u>L12</u>	374/180	149	<u>L12</u>
<u>L11</u>	film extends beyond substrate	2	<u>L11</u>
DB=PGP	PB; PLUR=YES; OP=ADJ		
<u>L10</u>	L1 and "stretch"	0	<u>L10</u>
<u>L9</u>	L1 and "tension"	0	<u>L9</u>
<u>L8</u>	L1 and "compressive"	0	<u>L8</u>
<u>L7</u>	L1 and "compression"	0	<u>L7</u>
<u>L6</u>	L1 and "tensile"	0	<u>L6</u>
DB=PGF	PB, USPT, USOC, EPAB, JPAB, DWPI, TDBD; PLUR=YES; O	P = ADJ	
<u>L5</u>	L4 and "thin film"	50	<u>L5</u>
<u>L4</u>	positive strain	803	<u>L4</u>

DB=PGPB; PLUR=YES; OP=ADJ

<u>L3</u>	L2 and "positive"	0	<u>L3</u>
<u>L2</u>	L1 and "0.006"	1	<u>L2</u>
<u>L1</u>	20040101022	1	<u>L1</u>

END OF SEARCH HISTORY